



Att. Docket No. 10191/1629

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. Serial No. : 09/720,761 Confirmation No. 5642
Title : METHOD OF PLASMA
ETCHING OF SILICON
Applicant(s) : Franz LAERMER et al.
Filed : March 26, 2001
TC/A.U. : 1765
Examiner : Kin Chan Chen
Docket No. : 10191/1629
Customer No. : 26646

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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AARON C. DEDITCH
(33,835)

AMENDMENT

S I R:

In response to the Office Action mailed on December 1, 2003 (the three-month response date for which has been extended by one month from March 1, 2004 to April 1, 2004 by the accompanying Transmittal and Petition To Extend), please reconsider the above-identified application based on the following:

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.